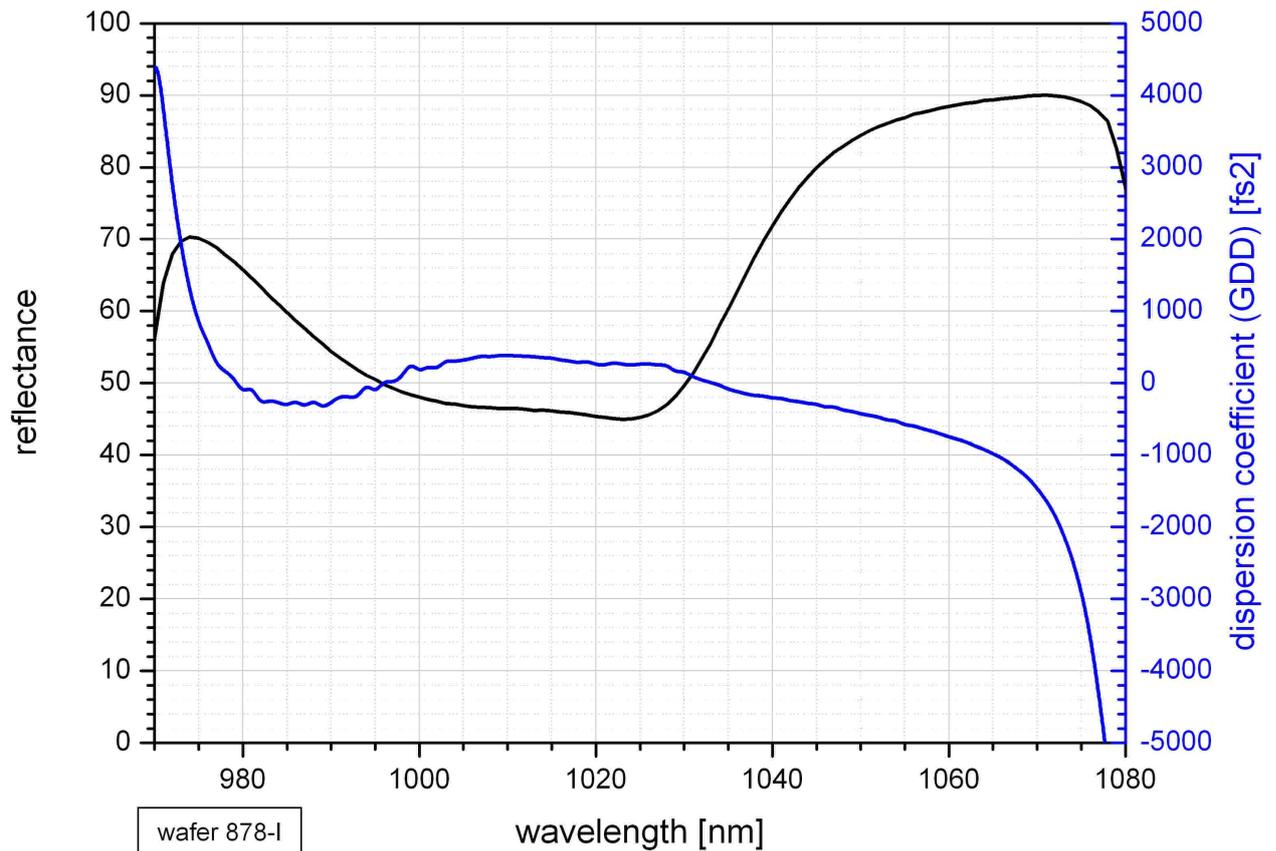


SAM™ Data Sheet SAM-1030-55-500fs-x, $\lambda = 1030 \text{ nm}$

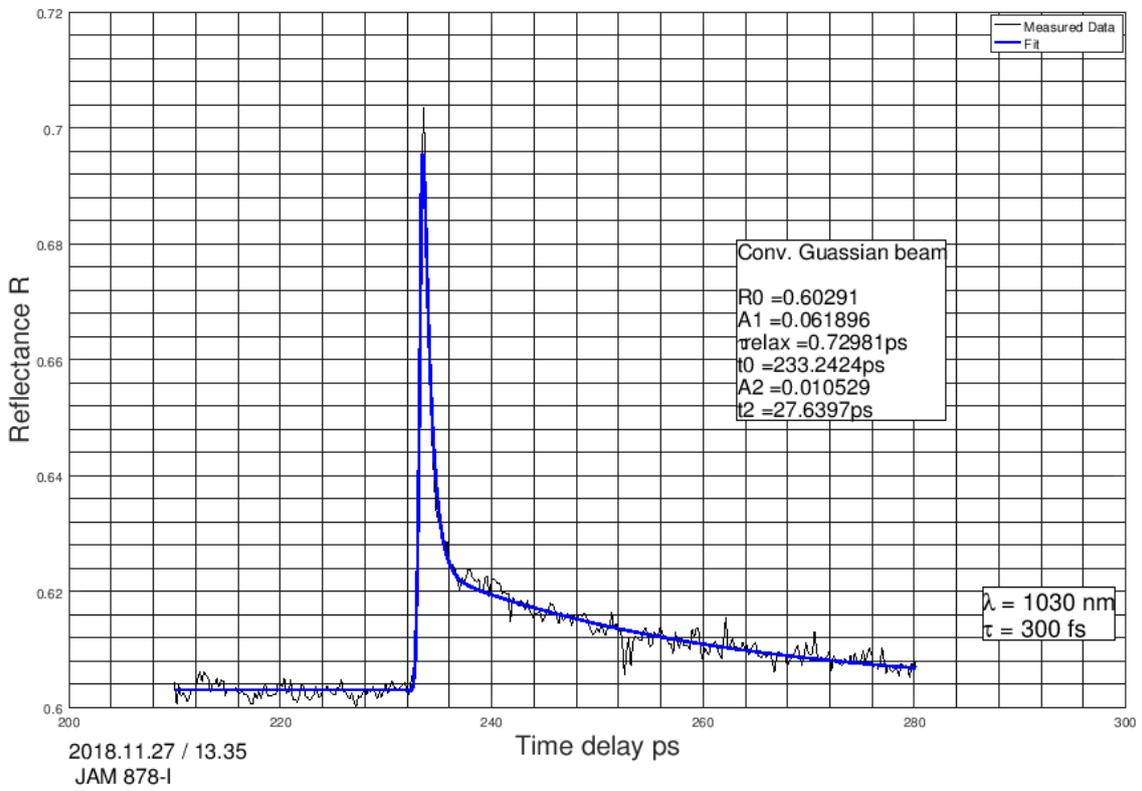
	Minimum	Typical Value	Maximum
Operational wavelength λ		1030 nm	
High reflection band	985 nm		1065 nm
Absorbance A	44 %	55 %	66 %
Modulation depth ΔR	24 %	30 %	36 %
Non-saturable loss A_{ns}	20 %	25 %	30 %
Saturation fluence Φ_{sat}	18 $\mu\text{J}/\text{cm}^2$	23 $\mu\text{J}/\text{cm}^2$	28 $\mu\text{J}/\text{cm}^2$
Relaxation time constant τ	500 fs	~ 700 fs	1 ps
Damage threshold Φ		800 $\mu\text{J}/\text{cm}^2$	
Absorber Peak Temperature			150°C ¹
Chip thickness	425 μm	450 μm	475 μm
Protection	SAM is protected with a dielectric front layer		

¹ Please make sure that this temperature is not exceeded in pulsed operation shortly after the optical pulse.

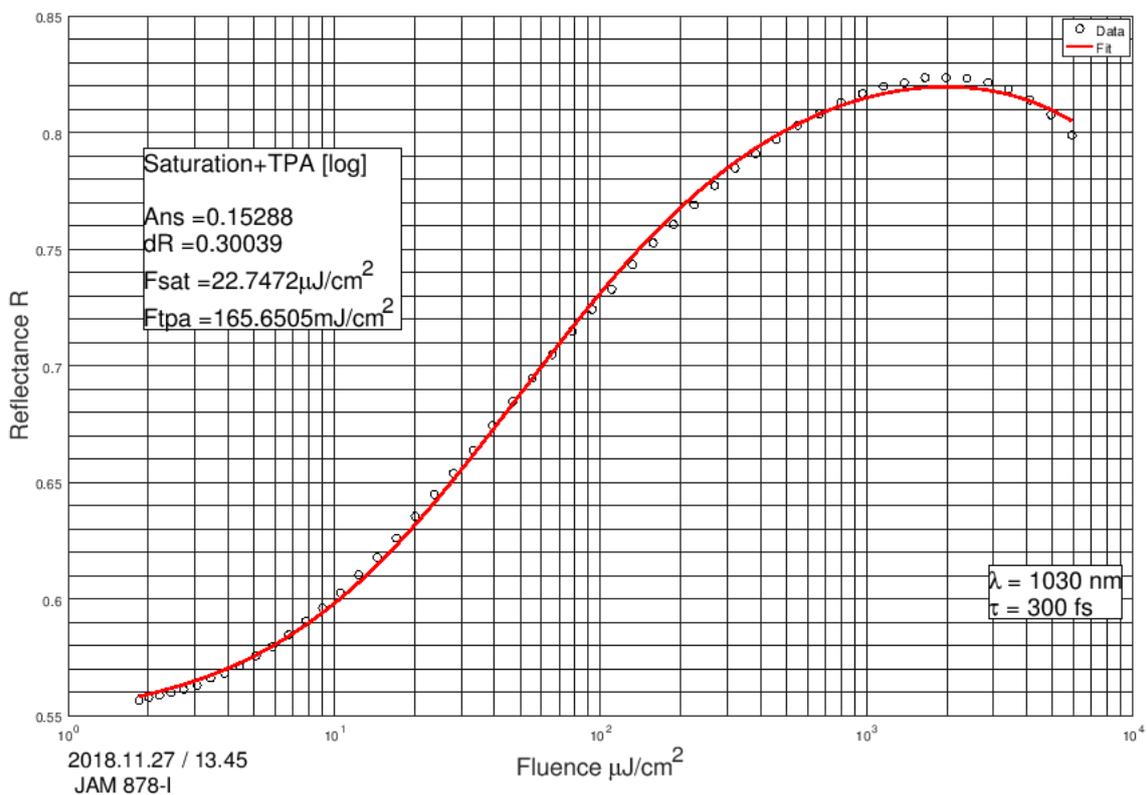
Low intensity spectral reflectance and dispersion

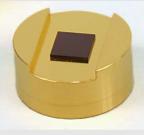
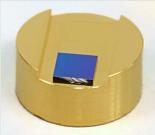


Relaxation time



Saturation measurement



Mounting Options SAM-1030-55-500fs-x	Description
x = 4.0-0	Single chip, unmounted, chip size 4.0mm x 4.0mm
x = 1.0b-0	Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm
x = 1.3b-0	Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm
x = 4.0-12.7g-c / 4.0-12.7g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm \varnothing
x = 4.0-25.0g-c / 4.0-25.0g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm \varnothing
x = 4.0-25.4g-c / 4.0-25.4g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm \varnothing
x = 4.0-12.7s-c / 4.0-12.7s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm \varnothing
x = 4.0-25.0s-c / 4.0-25.0s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm \varnothing
x = 4.0-25.4s-c / 4.0-25.4s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm \varnothing
x = 4.0-25.0w-c / 4.0-25.0w-e	chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter
x = 4.0-25.4h-c / 4.0-25.4h-e	chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application
-c Center mounting 	-e Edge mounting 
x = FC/PC / FC/APC	mounted on a 1 m monomode fiber cable with FC/PC / FC/APC connector available fiber types: HI 980, HI 1060, Fujikura SM98-PS-U25A (polarisation maintaining (PM) fiber)
Other chip dimensions are also possible, please ask.	